

Title (en)

Device for applying liquid glues to a substrate.

Title (de)

Vorrichtung zum Auftragen von flüssigen Klebstoffen auf ein Substrat.

Title (fr)

Dispositif pour appliquer des colles liquides sur un substrat.

Publication

EP 0297268 A2 19890104 (DE)

Application

EP 88108052 A 19880519

Priority

DE 3721593 A 19870630

Abstract (en)

[origin: JPS6430673A] PURPOSE: To enable the rapid adaptation to various layer thicknesses and viscosities of an adhesive by arranging a doctor blade which is built into an applicator nozzle and is easily removable and exchangeable by means of a clamp support in a slit-like discharge port. CONSTITUTION: Since an applicator head has a valve means, the hot melt discharged from the applicator nozzle 10 arranged in the bottom of the head is applied by as much as the exactly regulated amt. onto a web 32 moving forward under the nozzle 10. The hole 18 of one 12 of parallel plates 12, 14 of the nozzle 10 is connected via a passage 20 to a spreading chamber 22 where the coating thickness and width are regulated by a mask 24 consisting of spring sleet disposed between both plates 12 and 14. The clamp plate 28 presses the doctor blade 26 to the mask 24 via a clamp screw 30, the doctor blade 26 is thus easily removed and exchanged.

Abstract (de)

Die Vorrichtung weist einen Vorratsbehälter für den Klebstoff und eine über eine Leitung mit dem Vorratsbehälter verbundene Auftragsdüse (10) mit einer schlitzförmigen Austrittöffnung auf, die über einen Zuführkanal (20) mit einer Ausbreitkammer (22) in Verbindung steht; an der schlitzförmigen Auslaßöffnung ist ein durch eine Klemmhalterung (21, 30) befestigtes Rakelblech (26) angeordnet.

IPC 1-7

B05C 5/02; **B05C 5/04**; **B05C 11/04**; **D06B 15/08**

IPC 8 full level

B05C 1/02 (2006.01); **B05C 5/02** (2006.01); **B05C 11/02** (2006.01); **B05C 11/04** (2006.01); **B05C 11/10** (2006.01); **D06B 11/00** (2006.01)

CPC (source: EP US)

B05C 5/0262 (2013.01 - EP US); **B05C 11/10** (2013.01 - EP US); **D06B 11/0066** (2013.01 - EP US)

Cited by

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Designated contracting state (EPC)

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DOCDB simple family (publication)

EP 0297268 A2 19890104; **EP 0297268 A3 19900314**; DE 3721593 A1 19890126; DE 3721593 C2 19911107; JP 2608927 B2 19970514; JP S6430673 A 19890201; US 4876982 A 19891031

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